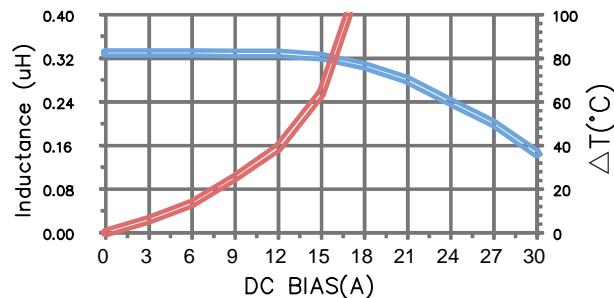
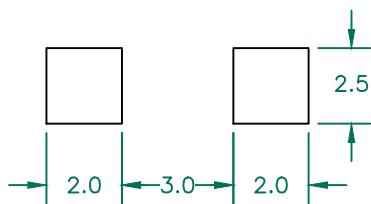


# MGV0502R33M-10

## PHYSICAL DIMENSIONS:

A	5.50	±	0.50
B	5.10	±	0.30
C	2.00	±	0.30
D	1.50	±	0.30
E	1.20	±	0.50

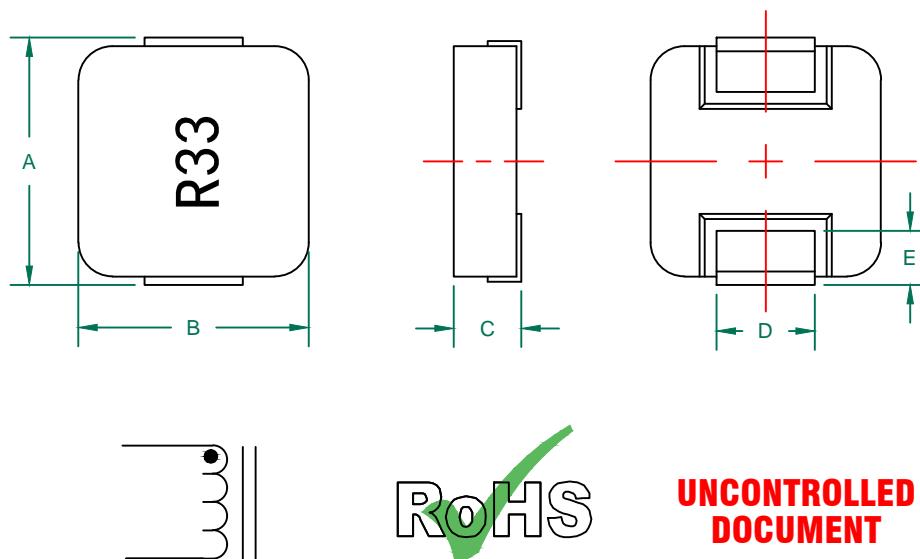
## LAND PATTERNS FOR REFLOW SOLDERING



## ELECTRICAL SPECIFICATION @ 25°C

	Min	Norm	Max
INDUCTANCE (uH) L @ 100 KHz/0.25V ± 20%	0.264	0.330	0.396
DCR (Ω)			0.0082

Saturation Current <sup>3</sup> Isat (A)	25.00
Temperature Rise Current Irms <sup>4</sup> (A)	12.00



**RoHS**

**UNCONTROLLED DOCUMENT**

NOTES: UNLESS OTHERWISE SPECIFIED

1. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
2. OPERATION TEMPERATURE RANGE:  
-40°C~+125°C (INCLUDING SELF-HEATING) .
3. DEFINITION OF SATURATION CURRENT (ISAT): DC CURRENT AT WHICH THE INDUCTANCE DROPS ≤25% FROM ITS VALUE WITHOUT CURRENT (Ta=25±5°C).
4. DEFINITION OF TEMPERATURE RISE CURRENT (IRMS): DC CURRENT THAT CAUSES THE TEMPERATURE RISE (ΔT ≤40°C) FROM 25°C AMBIENT.

DIMENSIONS ARE IN mm.				This print is the property of Laird Tech, and is loaned in confidence subject to return upon request and with the understanding that no copies shall be made without the written consent of Laird Tech. All rights to design or invention are reserved.			
D	UPDATE LOGO	04/22/15	QIU	PROJECT/PART NUMBER:	MGV0502R33M-10		
C	CHANGE NOTE 2.3.4	09/24/12	QIU	DATE:	04/25/12	SCALe:	NTS
B	REVISE DIMENSIONS	06/27/12	QIU	CAD #	MGV0502R33M-10-D	TOOL #	-
A	ORIGINAL DRAFT	04/25/12	QIU			SHEET: 1 of 1	
REV	DESCRIPTION	DATE	INT				